	Тур	L#	Hits	Search Text	DBs	Time Stamp
8	BRS	L28	96094	stress-relie\$5 or (stress near5	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 16:25
9	BRS	L35	2239	28 near10 (Cu or copper or Cu-alloy or copper-alloy or Cu-wiring or copper-wiring or interconnect\$4 or wiring or plug or metallization)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 16:29
10	BRS	L42	360	35 same (slot or opening or space or spacing or recess or trench or via or viahole)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 16:32

	Туре	L#	Hits	S arch Text	DBs	Time Stamp
1	BRS	L1	939546	stress-relie\$5 or (stress near5 (relie\$5 or reduc\$5 or enhanc\$4 or suppress\$4)) or slot	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 13:29
2	BRS	L8	34780	1 near20 (Cu or copper or Cu-alloy or copper-alloy or Cu-wiring or copper-wiring or interconnect\$4 or wiring or plug or metallization)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 13:36
3	BRS	L15	20009	8 and (semiconductor or IC or (intergrated adj circuit) or interconnect\$4 or metallization)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 13:33
4	BRS	L22	32575	8 same (slot or pattern\$4 or opening or space or spacing)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 13:35
5	BRS	L29	32575	8 and 22	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 13:35

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	Туре	L#	Hits	Search Text	DBs	Tim Stamp
6	BRS	L36	18622	15 and 22	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_TD B	2002/07/03 13:36
7	BRS	L43	3215	15 and 22	EPO; JPO; DERW ENT; IBM_TD B	
9	BRS	L55	8091	copper-wiring or interconnect\$4 or	DERW	2002/07/03 13:37
10	BRS	L60	2680	43 and 55	EPO; JPO; DERW ENT; IBM_TD B	3
11	BRS	L65	199	and (via or via-noie or vianoie) and (wire or wiring or interconnect\$4 or line)	:	2002/07/03 13:39

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